

REMARKS

Claim 4 has been further amended to correct the omission of the dependency.

Attached hereto is a clean copy of all claims as amended.

The Office is authorized to charge any underpayment or credit any overpayment to Kenyon & Kenyon's Deposit Account No. 11-0600.

Respectfully submitted,

A handwritten signature in dark ink, appearing to read "Mark H. Neblett", is written over a horizontal line.

Mark H. Neblett
(Reg. No. 42,028)

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KENYON & KENYON
1500 K Street, N.W., Suite 700
Washington, D.C. 20005
(202) 220-4200

WHAT IS CLAIMED IS:

1. A method of laser beam machining,
wherein a plurality of laser diode arrays are disposed in such a manner as to allow radiation of laser beams in a direction of a width of a part to be processed, and
wherein each of the laser diode arrays is controlled in accordance with the direction of the width of the part to be processed so as to shape laser beams and irradiate the part to be processed with the laser beams.
2. The method of laser beam machining according to claim 1,
wherein each of the laser diode arrays is controlled and laser beams are shaped such that distribution of energy is changed in accordance with a width position of the part to be processed.
3. The method of laser beam machining according to claim 2,
wherein the distribution of energy is changed by controlling each of the laser diode arrays and shaping the laser beams such that laser beams with which the part to be processed is irradiated in its widthwise marginal portions exhibit a higher intensity than laser beams with which the part to be processed is irradiated in its widthwise central portion.
4. The method of laser beam machining according to claim 1,
wherein laser beam machining is a processing which is selected from padding, welding and hardening and to which the part to be processed is subjected.
5. The method of laser beam machining according to claim 2,
wherein laser beam machining is a processing which is selected from padding, welding and hardening and to which the part to be processed is subjected.
6. The method of laser beam machining according to claim 3,
wherein laser beam machining is a processing which is selected from padding, welding and hardening and to which the part to be processed is subjected.